

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A) ^a	Q _g (Typ.)			
30	0.030 at V _{GS} = 10 V	6.5	4.5 nC			
30	0.033 at $V_{GS} = 4.5 \text{ V}$	6.0	4.5110			

FEATURES

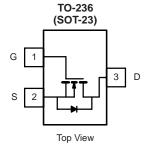
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

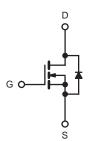


ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

DC/DC Converter





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V_{DS}	30	V		
Gate-Source Voltage		V_{GS}	± 20] v		
	T _C = 25 °C		6.5 ^a			
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	l _D	6.0			
Continuous Brain Carrette (1) = 100 °C)	T _A = 25 °C	d' 'D	5.3			
	T _A = 70 °C]	5.0	Α		
Pulsed Drain Current		I _{DM}	25			
	T _C = 25 °C		1.4			
Continuous Source-Drain Diode Current	T _A = 25 °C	IS	0.9 ^{b, c}			
	T _C = 25 °C		1.7			
Maximum Power Dissipation	$T_C = 70 ^{\circ}C$	P _D	1.1	w		
Maximum i ower bissipation	T _A = 25 °C	۵' ا	1.1 ^{b, c}] **		
	T _A = 70 °C]	0.7 ^{b, c}			
Operating Junction and Storage Temperatur	e Range	T _J , T _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Temperature) ^{d, e}			260			

THERMAL RESISTANCE RATINGS								
Parameter		Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	90	115	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	60	75	0, 11			

Notes:

- a. Package limited
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 130 °C/W.



SPECIFICATIONS $T_J = 25 ^{\circ}\text{C}$,				1			
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, I}_{D} = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		31		mV/°(
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$			- 5		11107	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	0.7	1.1	2.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	l	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate voltage Drain Current	I _{DSS}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α	
	D	$V_{GS} = 10 \text{ V, I}_{D} = 3.2 \text{ A}$		0.030			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 2.8 \text{ A}$		0.033		Ω	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_D = 4.8 \text{ A}$		11		S	
Dynamic ^b	·			1			
Input Capacitance	C _{iss}			335			
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		45		pF	
Reverse Transfer Capacitance	C _{rss}			17		pF 	
Total Oats Observe		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 3.4 \text{ A}$		4.5	6.7	pF - nC	
Total Gate Charge	Q_g			2.1	3.2		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 3.4 \text{ A}$		0.85		nC	
Gate-Drain Charge	Q_{gd}			0.65			
Gate Resistance	R _g	f = 1 MHz	0.8	4.4	8.8	Ω	
Turn-On Delay Time	t _{d(on)}			12	20		
Rise Time	t _r	V_{DD} = 15 V, R_L = 5.6 Ω		50	75		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 2.7 A, V_{GEN} = 4.5 V, R_g = 1 Ω		12	20		
Fall Time	t _f			22	35		
Turn-On Delay Time	t _{d(on)}			5	10	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 5.6 Ω		12	20		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 2.7 A, V_{GEN} = 10 V, R_g = 1 Ω		10	15		
Fall Time	t _f			5	10		
Drain-Source Body Diode Characteristi	cs						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			1.4	٨	
Pulse Diode Forward Current	I _{SM}				15	A	
Body Diode Voltage	V_{SD}	$I_S = 2.7 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			10	20	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 27 A dl/dt 100 A/vo T 25 °C		5	10	nC	
Reverse Recovery Fall Time	t _a	I _F = 2.7 A, αI/αt = 100 A/μs, I ₁ = 25 °C					
Reverse Recovery Rise Time	t _b			4		ns	

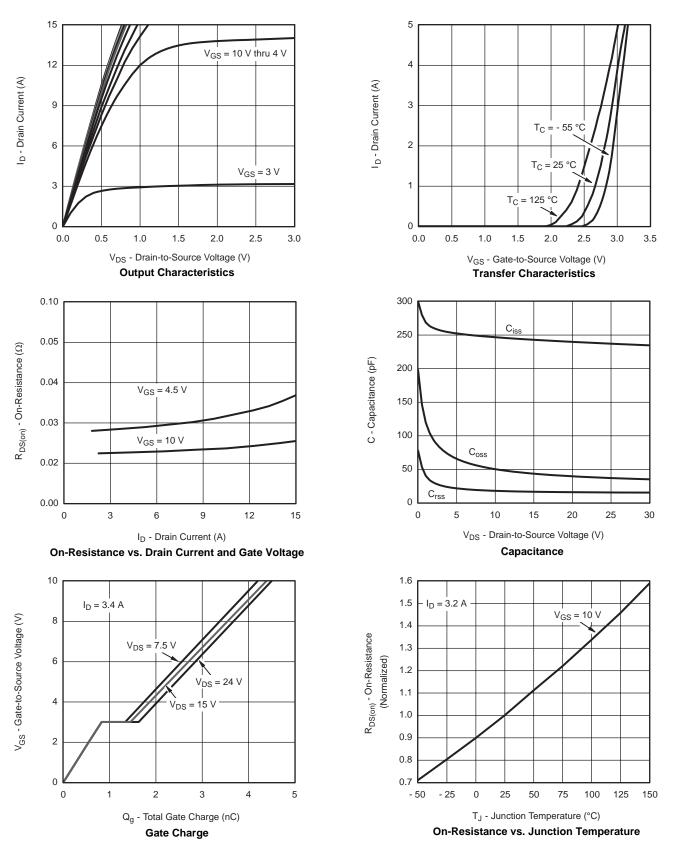
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

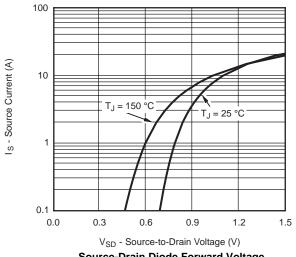




T_J = 125 °C

T_J = 25 °C

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





On-Resistance vs. Gate-to-Source Voltage

0.14

0.12

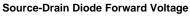
0.10

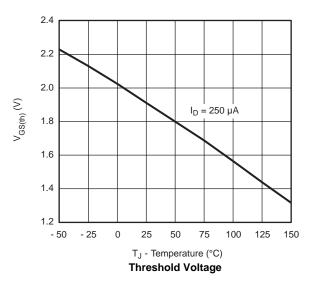
0.08

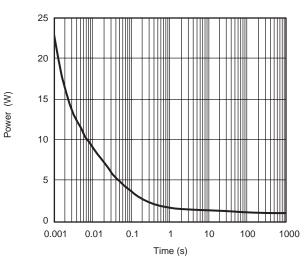
0.06

 $R_{DS(on)}$ - On-Resistance (Ω)

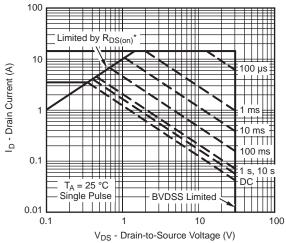
 $I_D = 3.2 \text{ A}$









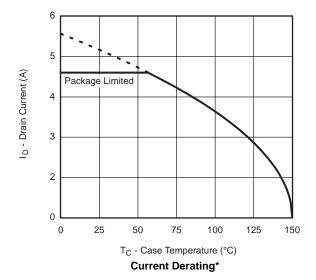


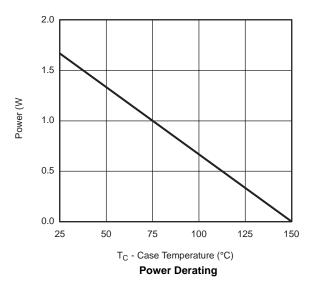
 * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

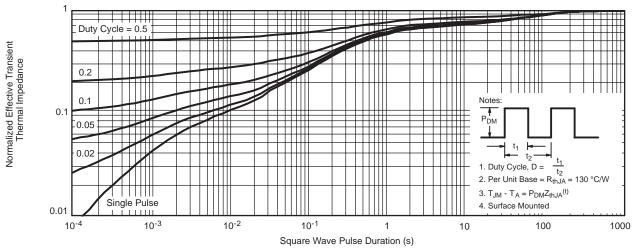




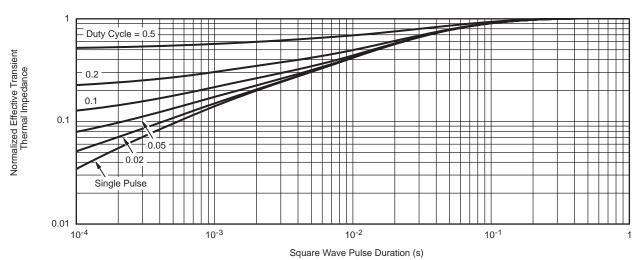
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



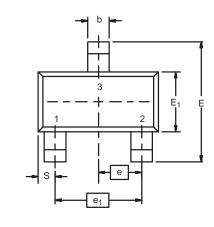
Normalized Thermal Transient Impedance, Junction-to-Ambient

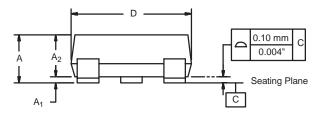


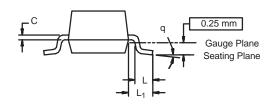
Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-23 (TO-236): 3-LEAD







Dim	MILLIM	IETERS	INCHES	
	Min	Max	Min	Max
Α	0.89	1.12	0.035	0.044
A ₁	0.01	0.10	0.0004	0.004
A ₂	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
С	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E ₁	1.20	1.40	0.047	0.055
е	0.95 BSC		0.037	4 Ref
e ₁	1.90	1.90 BSC		8 Ref
L	0.40	0.60	0.016	0.024
L ₁	0.64 Ref		0.025	Ref
S	0.50 Ref		0.020) Ref
q	3°	8°	3°	8°

ECN: S-03946-Rev. K, 09-Jul-01

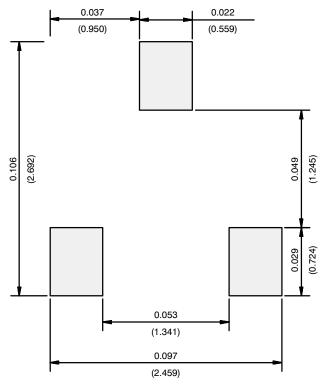
DWG: 5479

服务热线:400-655-8788

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RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
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BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
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